

Ultra-SB² 300 WLR[®]

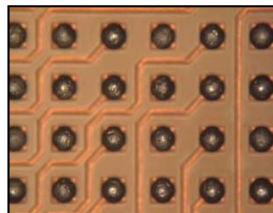
Wafer Level Solder Ball Rework

Equipment to improve solder ball attach yield to 100%.

- automatic wafer inspection
- removal of misplaced balls
- flux dispensing
- reballing of missing balls
- update of electronic wafer map
- ultra fast post ball inspection

Specifications:

- Wafer size: 6", 8", 12"
- Solder ball sizes: 60µm – 500µm
- 25 wafers/hour 12inch
- 30 wafers/hour 8 inch



Cassette to cassette
robot handling



400,000 I/O's, 80µm SnAgCu



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Pac Tech GmbH
Am Schlangenhorst 15-17
14641 Nauen
Germany



Tel: +49 (0)3321-4495-100
Fax: +49 (0)3321-4495-110
Email: sales@pactech.de

Pac Tech USA Inc.
328 Martin Avenue
Santa Clara, CA 95050
USA

Tel: +1 408-588-1925
Fax: +1 408-588-1927
Email: sales@pactech-usa.com

Pac Tech Asia Sdn. Bhd.
Plot 14, Medan Bayan Lepas
Technoplex, Phase 4
Bayan Lepas Industrial Zone
1190 Bayan Lepas, Penang
Malaysia

Tel: +60 (4) 6440 986
Fax: +60 (4) 6449 987
Email: sales@pactech-asia.com

Pac Tech Thailand (Service Center)
98/286 Moo 9
Romruengarden vill Sol 5
Chiangragnoi, Ayutthaya 13160
Thailand

Tel: +66 899275852
Fax: +66 357422768
Email: customer.service@pactech-asia.com